

IN THE CLAIMS

Please amend the claims as follows:

1. (Original) A semiconducting device comprising:
an interposer that includes a fold which divides the interposer into a first section and a second section;
a first die attached to a first surface of the interposer at the first section and the second section;
a contact attached to the first surface of the interposer at the first section and the second section;
a second die attached to a second surface of the interposer, the second die being stacked onto the first die and electrically coupled to the first die by the contact and conductive paths that are part of the interposer.
2. (Original) The semiconducting device of claim 1, wherein the contact is a solder column.
- 3-4. (Cancelled)
5. (Original) The semiconducting device of claim 1, further comprising a plurality of contacts that are each attached to the first surface of the interposer at the first section and the second section.
6. (Original) The semiconducting device of claim 5, wherein the fold is on one side of the first die and at least one of the contacts is on an opposite side of the first die.
7. (Original) The semiconducting device of claim 5, wherein at least one of the contacts is on each side of the first die.

8-20. (Cancelled)

21. (New) The semiconducting device of claim 1, wherein the contact is formed of a solder column and a pad.

22. (New) The semiconducting device of claim 1, wherein the contact extends between two different portions of the first surface.

23. (New) The semiconducting device of claim 1, wherein at least one of the contacts is on one side of the first die and at least one other of the contacts is on an opposing side of the first die.

24. (New) The semiconducting device of claim 1, wherein at least one of the contacts is on three sides of the first die.

25. (New) The semiconducting device of claim 1, wherein at least one of the contacts is on each side of the first die.

26. (New) A semiconducting device comprising:

an interposer that includes a fold which divides the interposer into a first section and a second section;

a first die attached to a first surface of the interposer at the first section and the second section;

a solder column attached to the first surface of the interposer at the first section and the second section;

a second die attached to a second surface of the interposer, the second die being stacked onto the first die and electrically coupled to the first die by the solder column and conductive paths that are part of the interposer.

27. (New) The semiconducting device of claim 26, further comprising a plurality of solder columns that are each attached to the first surface of the interposer at the first section and the second section.
28. (New) The semiconducting device of claim 27, wherein at least one of the solder columns is on each side of the first die.
29. (New) A semiconducting device comprising:
an interposer that includes a fold which divides the interposer into a first section and a second section;
a first die attached to a first surface of the interposer at the first section and the second section;
a plurality of contacts attached to the first surface of the interposer at the first section and the second section, the fold being on one side of the first die and at least one of the contacts being on an opposite side of the first die;
a second die attached to a second surface of the interposer, the second die being stacked onto the first die and electrically coupled to the first die by the plurality of contacts and conductive paths that are part of the interposer.
30. (New) The semiconducting device of claim 29, wherein each of plurality of contacts is a solder column.
31. (New) The semiconducting device of claim 30, wherein at least one of the contacts is on each side of the first die.